

**Remarks/Arguments:**

Claims 1-3, 5-6, 8 and 10-24 are pending in the above-identified application. Claims 4, 7 and 9 have been cancelled. Claims 1 and 17 have been amended. Accordingly, claims 1-3, 5-6, 8 and 10-24 are presented for reconsideration. New claims 25-27 have been added and are presented for consideration.

Claims 17, 20 and 24 were rejected under 35 U.S.C. § 102 (b) as being anticipated by Asahi. Claim 17 is amended to recite features neither disclosed nor suggested by the prior art, namely:

... a step of forming a first sealing member covering a first circuit block of the plurality of circuit blocks individually in such a manner as to be higher than the mounting components **after the step of mounting the partition**  
...

... a step of forming a second sealing member covering a second circuit block of the plurality of circuit blocks individually in such a manner as to be higher than the mounting components **after the step of mounting the partition**. (Emphasis added).

Basis for this amendment may be found, for example, at page 7, lines 2-7 and Fig. 1, step 102 of the originally filed specification. No new matter has been added.

In the method of Applicants' exemplary embodiment, a partition 13 along with components 12 is mounted onto substrate 11. (Page 5, last line to page 6, line 8, and FIG. 1, step 101). First and second sealing members 14 are then formed on each side of the partition 13 after the partition is mounted. (Page 7, lines 2-7 and Fig. 1, step 102). Thus, claim 17 has been amended to recite that the first and second sealing members are formed "... after the step of mounting the partition ..."

The Office Action interprets Asahi's insulating layer 201 as being the same as Applicants' claimed "first sealing member" and "second sealing member." The Office Action also interprets the conductive via paste 203 (filled in hole 207) as being the same as Applicants' claimed "partition." (Office Action, page 2, item 2). Insulating layer 201 in Asahi, however, is formed before the partition is mounted. (FIG. 2A and FIG. 2B). In FIG. 2A, a through hole 207 is formed into the existing insulating layer

201. (Paragraph [0051]). Conductive via paste 203 (partition) is then filled into through hole 207, after sealing member 201 has been formed. (Fig. 2B). Thus, Asahi does not disclose forming first and second sealing members "... after the step of mounting the partition," as recited in amended claim 17. Applicants' claimed features are advantageous over the prior art of record because metal film 2 and ground pattern 5 may be made electrically continuous with each other without the additional costly step of filling a through hole to prevent vulnerability to breakage.

Thus, Applicants respectfully submit that claim 17 is allowable over the art of record. Claims 20 and 24 depend from claim 17. Accordingly, claims 20 and 24 are likewise allowable over the art of record.

Claims 1, 8, 10-12, 14, 16 and 22 were rejected under 35 U.S.C. § 102 (e) as being anticipated by Higashitani. Claim 1 is amended to recite features neither disclosed nor suggested by the prior art, namely:

... a first conductive film covering at least a surface of the first sealing member and **being continuous from the partition to the substrate** ...

... a second conductive film covering at least a surface of the second sealing member and **being continuous from the partition to the substrate**. (Emphasis added).

Basis for this amendment may be found, for example, at page 7, lines 2-7 and Fig. 1, step 102 of the originally filed specification. No new matter has been added.

First and second conductive films 16 of Applicants' exemplary embodiment are each formed continuously from the partition 13 to the substrate 11. That is, each conductive film is formed continuously from the partition 13 along a top surface and a side surface of the respective sealing members to the substrate 11. (FIG. 1, step 104). Thus, claim 1 recites a first conductive film and a second conductive film "... being continuous from the partition to the substrate ..."

The Office Action admits in the rejection of claim 21 that Higashitani does not disclose that the first and second conductive films are separated by the partition. (Page 9, item 10, lines 4-6). However, the Office Action argues that Asahi discloses

these features. The Office Action interprets the wiring patterns 202 in Asahi as being the same as Applicants' claimed "first conductive film" and "second conductive film." (Office Action, page 9, item 10). Each of the wiring patterns 202, however, are spaced apart from each other. That is, each of the wiring patterns to the left and right of partition 203 are not formed continuously from the partition to a substrate. Accordingly, neither Higashitani, Asahi, nor their combination disclose or suggest "... first conductive film and a second conductive film "... being continuous from the partition to the substrate ..."

Thus, Applicants respectfully submit that claim 1 is allowable over the art of record. Claims 8, 10-12, 14, 16 and 22 ultimately depend from claim 1. Accordingly, claims 8, 10-12, 14, 16 and 22 are likewise allowable over the art of record.

Claims 2, 5 and 15 were rejected under 35 U.S.C. § 103 (a) as being obvious over the combination of Higashitani and Glenn. Glenn is cited for its teaching of a sealing member and partition containing the same resin. Glenn does not make up for the deficiencies of Higashitani, as described above with respect to claim 1. Claims 2, 5 and 15 ultimately depend from claim 1. Accordingly, claims 2, 5 and 15 are also allowable at least because they depend from allowable claim 1.

Claims 6 and 13 were rejected under 35 U.S.C. § 103 (a) as being obvious over the combination of Higashitani and Yean. Yean is cited for its teaching of a resin partition having a metal film. Yean does not make up for the deficiencies of Higashitani, as described above with respect to claim 1. Claims 6 and 13 depend from claim 1. Accordingly, claims 6 and 13 are also allowable at least because they depend from allowable claim 1.

Claim 18 was rejected under 35 U.S.C. § 103 (a) as being obvious over Asahi and Yean. Yean is cited for its teaching of a conductive material formed vertical to the substrate. Yean does not make up for the deficiencies of Asahi, as described above with respect to claim 17. Claim 18 depends from claim 17. Accordingly, claim 18 is also allowable at least because it depends from allowable claim 17.

Claim 19 was rejected under 35 U.S.C. § 103 (a) as being obvious over Asahi and Ohmi. Ohmi is cited for its teaching of removal by laser. Ohmi does not make up

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for the deficiencies of Asahi, as described above with respect to claim 17. Claim 19 depends from claim 17. Accordingly, claim 19 is also allowable at least because it depends from allowable claim 17.

Claims 21 and 23 were rejected under 35 U.S.C. § 103 (a) as being obvious over the combination of Higashitani and Asahi. As described above, neither Higashitani, Asahi, nor their combination disclose or suggest the features of claim 1. Claims 21 and 23 depend from claim 1. Accordingly, claims 21 and 23 are also allowable at least because they depend from allowable claim 1.

Applicants appreciate the indication in the Office Action that claim 3 would be allowable if amended to be independent and to include all of the limitations of its base claim and any intervening claims. Because, as described above, claim 1 is in condition for allowance, no amendment to claim 3 is necessary.

New claims 25-27 have been added. Basis for claims 25-27 may be found, for example, at page 7, lines 2-16 and Fig. 1 of the originally filed specification. No new matter has been added. Entry of claims 25-27 is respectfully requested.

In view of the amendments and arguments set forth above, Applicants submit the above-identified application is in condition for allowance, which action is respectfully requested.

Respectfully submitted,



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